



**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q73159

Hien Boon TAN , et al.

Appln. No.: 10/721,384

Group Art Unit: 2826

Confirmation No.: 6008

Examiner: Alexander O. Williams

Filed: November 26, 2003

For: HIGH PERFORMANCE CHIP SCALE LEADFRAME PACKAGE AND METHOD OF  
MANUFACTURING THE PACKAGE

**RESPONSE TO ELECTION REQUIREMENT AND**  
**AMENDMENT UNDER 37 C.F.R. § 1.111**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This Amendment and Response is submitted in response to the Office Action dated  
December 28, 2004, in which Examiner set a shortened statutory period for reply of one month,  
making a response timely if filed before or on January 28, 2005.

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